Gap Pad® 2200SF

Thermally Conductive, Silicone-Free Gap Filling Material

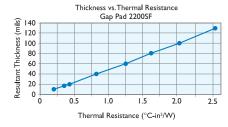
Features and Benefits

- Thermal conductivity: 2.0 W/m-K
- Silicone-free formulation
- Medium compliance with easy handling
- · Electrically isolating



Gap Pad 2200SF is a thermally conductive, electrically isolating, silicone-free polymer specially designed for silicone-sensitive applications. The material is ideal for applications with uneven topologies and high stackup tolerances. Gap Pad 2200SF is reinforced for easy material handling and added durability during assembly. The material is available with a protective liner on both sides. Gap Pad 2200SF is supplied with reduced tack on one side allowing for burn-in processes and easy rework.

Note: Resultant thickness is defined as the final gap thickness of the application.



| TYPICAL PROPERTIES OF GAP PAD 2200SF | | | |
|--|----------------|----------------|-------------|
| PROPERTY | IMPERIAL VALUE | METRIC VALUE | TEST METHOD |
| Color | Green | Green | Visual |
| Reinforcement Carrier | Fiberglass | Fiberglass | _ |
| Thickness (inch) / (mm) | 0.010 to 0.125 | 0.254 to 3.175 | ASTM D374 |
| Inherent Surface Tack (1 or 2 sided) | 2 | 2 | _ |
| Density (g/cc) | 2.8 | 2.8 | ASTM D792 |
| Heat Capacity (J/g-K) | 1.0 | 1.0 | ASTM E1269 |
| Hardness, Bulk Rubber (Shore 00) (1) | 70 | 70 | ASTM D2240 |
| Young's Modulus (psi) / (kPa) (2) | 33 | 228 | ASTM D575 |
| Continuous Use Temp (°F) / (°C) | -76 to 257 | -60 to 125 | _ |
| ELECTRICAL | | | |
| Dielectric Breakdown Voltage (Vac) | >5000 | >5000 | ASTM D149 |
| Dielectric Constant (1000 Hz) | 6.0 | 6.0 | ASTM DI50 |
| Volume Resistivity (Ohm-meter) | 108 | 108 | ASTM D257 |
| Flame Rating | V-O | V-O | U.L. 94 |
| THERMAL | | | |
| Thermal Conductivity (W/m-K) | 2.0 | 2.0 | ASTM D5470 |
| 1) Thint: accord delay yelve Chance OO hands are seele | | | |

- 1) Thirty second delay value Shore 00 hardness scale.
- Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116.

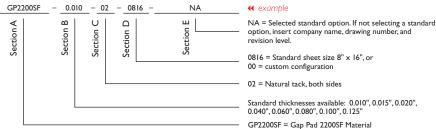
Typical Applications:

- · Digital disk drives
- Proximity near electrical contacts (e.g. DC brush motors, connectors, relays)
- Fiber optics modules

Configurations Available:

- Sheet form
- Die-cut parts
- Standard sheet size is 8" x 16"

Building a Part Number Standard Options



Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others

